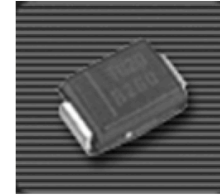


## Features

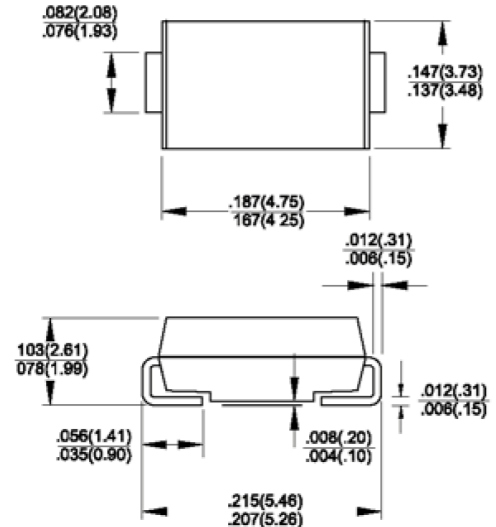
- ◆ Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low profile package
- ◆ Built-in strain relief, ideal for automated placement
- ◆ Glass passivated chip junction
- ◆ High temperature soldering: 250°C/10 seconds at terminals



**DO-214AA (SMB)**

## Mechanical Data

- ◆ Case: JEDEC DO-214AA (SMB) molded plastic body over glass passivated chip
- ◆ Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ Polarity: Color band denotes cathode end
- ◆ Weight: 0.003 ounce, 0.093 gram



## Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

| Parameter  | Symbols                            | GNOA        | GNOB | GNOD | GNOG | GNOJ | GNOK | GNOM | Units              |
|--|------------------------------------|-------------|------|------|------|------|------|------|--------------------|
| Maximum repetitive peak reverse voltage  | $V_{RRM}$                          | 50          | 100  | 200  | 400  | 600  | 800  | 1000 | Volts              |
| Maximum RMS voltage  | $V_{RMS}$                          | 35          | 70   | 140  | 280  | 420  | 560  | 700  | Volts              |
| Maximum DC blocking voltage  | $V_{DC}$                           | 50          | 100  | 200  | 400  | 600  | 800  | 1000 | Volts              |
| Maximum average forward rectified current at $T_L=100^\circ\text{C}$   | $I_{F(AV)}$                        | 1.5         |      |      |      |      |      |      | Amps               |
| Peak forward surge current<br>8.3ms single half sine-wave superimposed<br>on rated load (JEDEC Method) $T_L=100^\circ\text{C}$ | $I_{FSM}$                          | 50.0        |      |      |      |      |      |      | Amps               |
| Maximum instantaneous forward voltage at 1.5A  | $V_F$                              | 1.15        |      |      |      |      |      |      | Volts              |
| Maximum DC reverse current<br>@ $T_A=25^\circ\text{C}$<br>at rated DC blocking voltage<br>@ $T_A=125^\circ\text{C}$            | $I_R$                              | 1.0<br>125  |      |      |      |      |      |      | $\mu\text{A}$      |
| Typical reverse recovery time at<br>$I_F=0.5\text{A}$ , $I_R=1.0\text{A}$ , $I_T=0.25\text{A}$                                 | $t_{rr}$                           | 1.0         |      |      |      |      |      |      | $\mu\text{s}$      |
| Typical junction capacitance at 4.0V, 1MHz   | $C_J$                              | 30          |      |      |      |      |      |      | pF                 |
| Typical thermal resistance (NOTE 1)  | $R_{\theta JA}$<br>$R_{\theta JL}$ | 53<br>16    |      |      |      |      |      |      | $^\circ\text{C/W}$ |
| Operating junction temperature range   | $T_J$                              | -55 to +150 |      |      |      |      |      |      | $^\circ\text{C}$   |
| Storage temperature range  | $T_{STG}$                          | -55 to +150 |      |      |      |      |      |      | $^\circ\text{C}$   |

**Notes:** 1. Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3 x 0.3" (8.0 x 8.0mm) copper pad areas

